

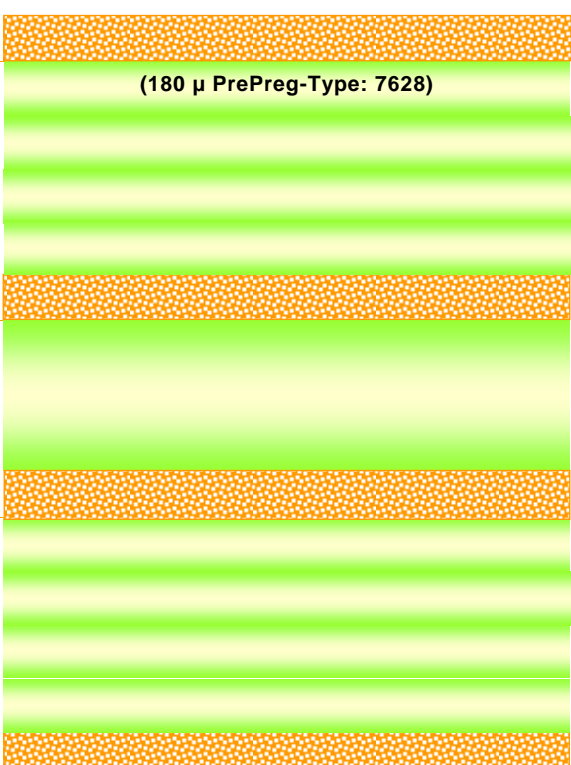

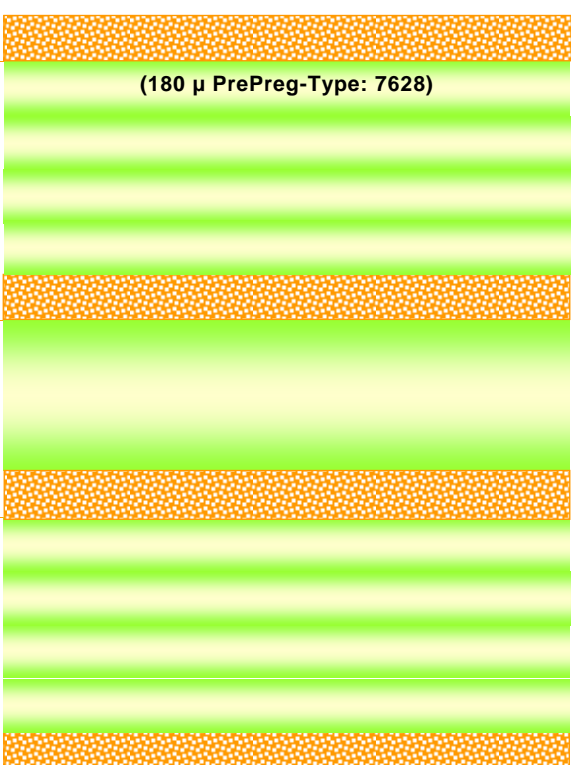

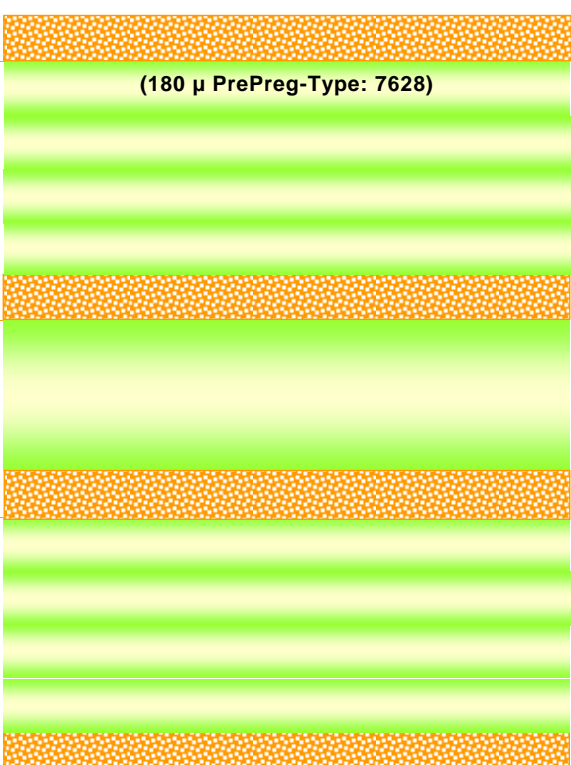

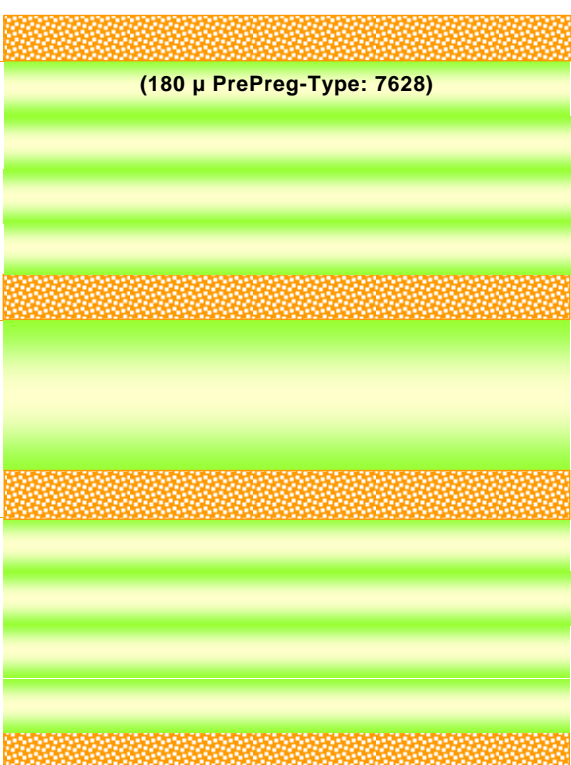

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

04 269 FR4 135 L71.135 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_269_FR4_135_L71.135_p18

Layers	in μ	Material	Build-Up	Assembly
Layer-1	135 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-2	135 μ	Copper		
	710 μ	L-FR4		
Layer-3	135 μ	Copper		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
	180 μ	Prepreg		
Layer-99	135 μ	Copper		

© Copyright by Printed Circuit Boards GmbH